

# SEMICONDUCTOR



APRIL 2007

FOCUSED ON EMERGING SEMICONDUCTOR COMPANIES

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## Radar Scope

### Air Semi

Air Semiconductor was founded in May 2006 to develop “a unique and disruptive approach to an emerging problem in cell phones.” The company has received funding from Pond Ventures and will seek additional capital in the future. The company was incubated in the University of Bath in Swindon’s Innovation Centre and SETsquared Business Acceleration Centre. Air currently has 9 employees.

David Tester, Founder & CEO (most recently a semiconductor designer and manager at Dialog Semi)

Stephen Graham, Co-founder & VP of Marketing (previously held marketing roles at marketing at Renesas Europe)

Cherry Orchard West  
Kembrey Park  
Swindon SN2 8UP  
United Kingdom  
Tel: +44 7947 864144  
Fax: +44 1793 474521  
www.air-semi.com

### BeSang

BeSang was founded as a fabless semiconductor IP company to develop 3D technology that allows memory to be stacked on top of the logic layer within a semiconductor device. BeSang’s mission is “to provide unique and sustainable technical solutions that can significantly reduce manufacturing costs of semiconductor chips, which include ultra high density memories.” The company has received funding from Northwest Technology Ventures.

BeSang’s 3-Dimensional Enabling Technology allows simple and large functional blocks (i.e. memory core or photo diode) to be placed on top of the logic layer within a semiconductor device. The technology is based on the logic layer in a silicon substrate, conventional vias for vertical interconnect, and a silicon thin layer containing the memory array.

Conventional 3D chip technologies are merely package-level stacking technologies, which are useful for limited mobile applications. In contrast, BeSang’s 3D technology stacks multi-layer devices within a single chip, using seamless

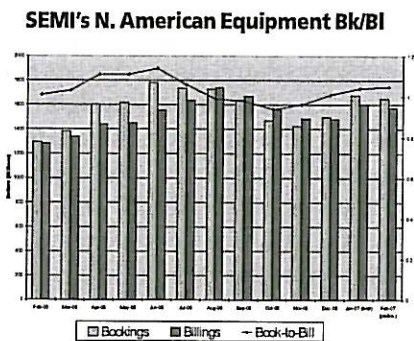
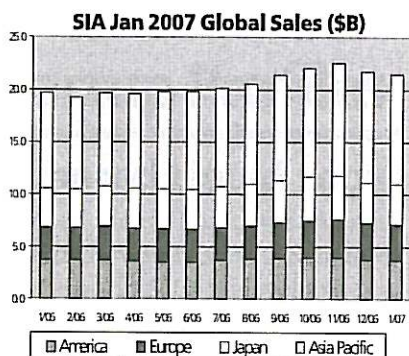
and unlimited interconnections between the device layers using conventional vias. As a result, this single-chip, high-density 3D technology provides a low-cost, high-speed vertical memory solution.

BeSang and the College of Nanoscale Science and Engineering (“CNSE”) of the University at Albany have formed a joint R&D partnership. As part of a three-year program valued at \$1.1 million, BeSang will use tools and facilities at CNSE’s Albany NanoTech complex to enhance its 3D technology.

Stay tuned – more info coming next month.

Sang-Yun Lee, Ph.D., President & CEO (previously held various engineering positions at Samsung, Motorola, and IDT)

Junil Park, Director of Process Technology (more than 16 years engineering and management experience at Samsung)



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